Composite Transistors

Panasonic

UP01113

Silicon PNP epitaxial planar type

For digital circuits

Features

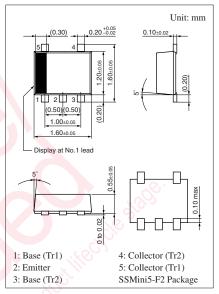
- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

Basic Part Number

• UNR1113 × 2

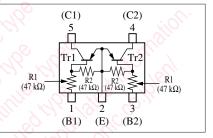
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	-50	v
Collector-emitter voltage (Base open)	V _{CEO}	-50	V
Collector current	I _C	-100	mA
Total power dissipation	P _T	125	mW
Junction temperature	Тј	125	°C
Storage temperature	T _{stg}	-55 to +125	°C



Marking Symbol: 7L

Internal Connection



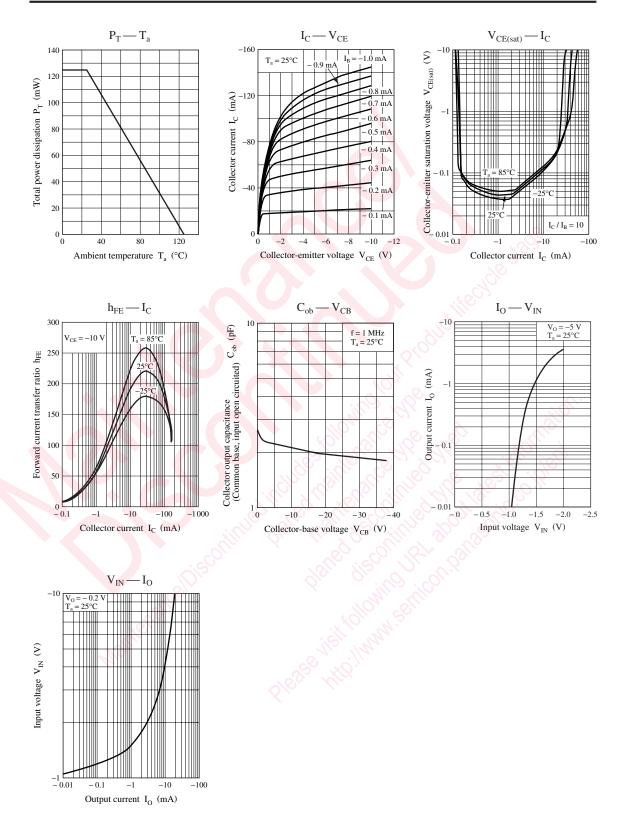
Parameter Symbol Conditions Min Max Unit Тур v Collector-base voltage (Emitter open) $I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$ -50V_{CBO} Collector-emitter voltage (Base open) V_{CEO} $I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$ -50V Collector-base cutoff current (Emitter open) $V_{CB} = -50 \text{ V}, I_E = 0$ - 0.1 I_{CBO} μΑ $V_{CE} = -50 \text{ V}, I_B = 0$ Collector-emitter cutoff current (Base open) I_{CEO} -0.5μΑ $V_{EB} = -6 V, I_C = 0$ Emitter-base cutoff current (Collector open) - 0.1 $I_{\rm EBO}$ mA $V_{CE} = -10 V, I_C = -5 mA$ Forward current transfer ratio 80 h_{FE} Collector-emitter saturation voltage $I_{C} = -10 \text{ mA}, I_{B} = -0.3 \text{ mA}$ -0.25v V_{CE(sat)} $V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$ Output voltage high-level -4.9v VOH VOL Output voltage low-level $V_{CC} = -5 \text{ V}, V_B = -3.5 \text{ V}, R_L = 1 \text{ k}\Omega$ -0.2V Input resistance R_1 -30% 47 +30% kΩ Resistance ratio R_1 / R_2 0.8 1.0 1.2 Transition frequency \mathbf{f}_{T} $V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$ 80 MHz

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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